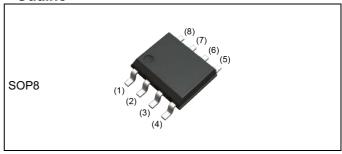
Pch -30V -7.5A Middle Power MOSFET

| V <sub>DSS</sub>           | -30V   |
|----------------------------|--------|
| R <sub>DS(on)</sub> (Max.) | 23.5mΩ |
| I <sub>D</sub>             | ±7.5A  |
| $P_D$                      | 2.0W   |

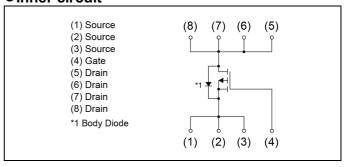
Features

- 1) Low on resistance.
- 2) Small Surface Mount Package (SOP8).
- 3) Pb-free lead plating; RoHS compliant.

### Outline



# ●Inner circuit



Packaging specifications

|      | Packing                   | Embossed<br>Tape |
|------|---------------------------|------------------|
|      | Reel size (mm)            | 330              |
| Туре | Tape width (mm)           | 12               |
| -    | Basic ordering unit (pcs) | 2500             |
|      | Taping code               | ТВ               |
|      | Marking                   | RS3E075AT        |

# Application

Switching

# ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

| Parameter  | Symbol             | Value       | Unit |
|--|--------------------|-------------|------|
| Drain - Source voltage                           | $V_{DSS}$          | -30         | V    |
| Continuous drain current                         | I <sub>D</sub>     | ±7.5        | Α    |
| Pulsed drain current                             | I <sub>DP</sub> *2 | ±30         | Α    |
| Gate - Source voltage                            | $V_{GSS}$          | ±20         | V    |
| Avalanche current, single pulse                  | I <sub>AS</sub> *3 | -7.5        | Α    |
| Avalanche energy, single pulse                   | E <sub>AS</sub> *3 | 4.2         | mJ   |
| Power dissipation                                | P <sub>D</sub> *4  | 2.0         | W    |
| Junction temperature                             | T <sub>j</sub>     | 150         | °C   |
| Operating junction and storage temperature range | T <sub>stg</sub>   | -55 to +150 | °C   |

# ●Thermal resistance

| Doromotor                              | Cymphol              | Values |      |      | Lloit |
|--|----------------------|--------|------|------|-------|
| Parameter                              | Symbol               | Min.   | Тур. | Max. | Unit  |
| Thermal resistance, junction - ambient | R <sub>thJA</sub> *4 | -      | 62.5 | -    | °C/W  |

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

| Daramatar                                      | Cymah al                                  | Conditions                                    | Values |      | Values |       |
|--|---|---|--------|------|--------|-------|
| Parameter                                      | Symbol                                    | Conditions                                    | Min.   | Тур. | Max.   | Unit  |
| Drain - Source breakdown voltage               | V <sub>(BR)DSS</sub>                      | $V_{GS} = 0V$ , $I_D = -1mA$                  | -30    | -    | -      | V     |
| Breakdown voltage temperature coefficient      | $\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$ | I <sub>D</sub> = -1mA<br>referenced to 25°C   | -      | -22  | -      | mV/°C |
| Zero gate voltage drain current                | I <sub>DSS</sub>                          | $V_{DS} = -30V, V_{GS} = 0V$                  | -      | -    | -1     | μΑ    |
| Gate - Source leakage current                  | I <sub>GSS</sub>                          | $V_{GS}$ = ±20V, $V_{DS}$ = 0V                | -      | -    | ±100   | nA    |
| Gate threshold voltage                         | $V_{GS(th)}$                              | $V_{DS} = -10, I_{D} = -1 \text{mA}$          | -1.0   | -    | -2.5   | V     |
| Gate threshold voltage temperature coefficient | $\frac{\DeltaV_{GS(th)}}{\DeltaT_j}$      | I <sub>D</sub> = -1mA<br>referenced to 25°C   | -      | 2.9  | -      | mV/°C |
| Static drain - source                          | D *5                                      | $V_{GS} = -10V, I_D = -7.5A$                  | 1      | 18.0 | 23.5   | mΩ    |
| on - state resistance                          | R <sub>DS(on)</sub> *5                    | $V_{GS} = -4.5V, I_D = -7.5A$                 | 1      | 24.0 | 31.0   | 11122 |
| Forward Transfer<br>Admittance                 | Y <sub>fs</sub>  *5                       | V <sub>DS</sub> = -5V, I <sub>D</sub> = -7.5A | 7.5    | -    | -      | S     |

<sup>\*1</sup> Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw  $\leq$  10µs, Duty cycle  $\leq$  1%

<sup>\*3</sup> L  $^{\sim}$  100 $\mu$ H, V $_{DD}$  = -15V, R $_{G}$  = 25 $\Omega$ , STARTING T $_{ch}$  = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*4</sup> Mounted on a ceramic boad (30×30×0.8mm)

<sup>\*5</sup> Pulsed

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

| Darameter                    | Cumbal                   | Conditions                                    | Values |      |      | Unit  |  |
|------------------------------|--------------------------|---|--------|------|------|-------|--|
| Parameter                    | Symbol Conditions        |   | Min.   | Тур. | Max. | UTIIL |  |
| Input capacitance            | C <sub>iss</sub>         | V <sub>GS</sub> = 0V                          | -      | 1250 | 1    |       |  |
| Output capacitance           | C <sub>oss</sub>         | V <sub>DS</sub> = -15V                        | -      | 220  | -    | pF    |  |
| Reverse transfer capacitance | C <sub>rss</sub>         | f = 1MHz                                      | -      | 170  | -    |       |  |
| Turn - on delay time         | t <sub>d(on)</sub> *5    | V <sub>DD</sub> ≈ -15V,V <sub>GS</sub> = -10V | -      | 10   | -    |       |  |
| Rise time                    | <b>t</b> <sub>r</sub> *5 | I <sub>D</sub> = -3.75A                       | -      | 20   | -    |       |  |
| Turn - off delay time        | t <sub>d(off)</sub> *5   | $R_L \simeq 4\Omega$                          | -      | 80   | -    | ns    |  |
| Fall time                    | <b>t</b> <sub>f</sub> *5 | $R_G = 10\Omega$                              | -      | 60   | -    |       |  |

# ● Gate charge characteristics (T<sub>a</sub> = 25°C)

| Doromotor            | Cumbal             | Conditions             |                         | Values |      |      | Unit  |
|----------------------|--------------------|------------------------|-------------------------|--------|------|------|-------|
| Parameter            | Symbol             |                        |                         | Min.   | Тур. | Max. | Offic |
| Total gate above     | O *5               |                        | V <sub>GS</sub> = -10V  | -      | 25   | -    |       |
| Total gate charge    | $Q_g^{*5}$         | V <sub>DD</sub> ≃ -15V |                         | -      | 12.8 | -    | »C    |
| Gate - Source charge | Q <sub>gs</sub> *5 | I <sub>D</sub> = -7.5A | V <sub>GS</sub> = -4.5V | -      | 4.5  | -    | nC    |
| Gate - Drain charge  | Q <sub>gd</sub> *5 |                        |                         | -      | 4.7  | -    |       |

# ●Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

| Parameter                  | Symbol             | Conditions                                    | Values |      |       | Unit  |
|----------------------------|--------------------|---|--------|------|-------|-------|
| Parameter                  | Symbol             | Conditions                                    | Min.   | Тур. | Max.  | Uffil |
| Continuous forward current | I <sub>S</sub> *1  | T = 25°C                                      | -      | -    | -1.67 | Α     |
| Pulse forward current      | I <sub>SP</sub> *2 | T <sub>a</sub> = 25℃                          | -      | -    | -30   | Α     |
| Forward voltage            | V <sub>SD</sub> *5 | V <sub>GS</sub> = 0V, I <sub>S</sub> = -1.67A | -      | -    | -1.2  | V     |

Fig.1 Power Dissipation Derating Curve

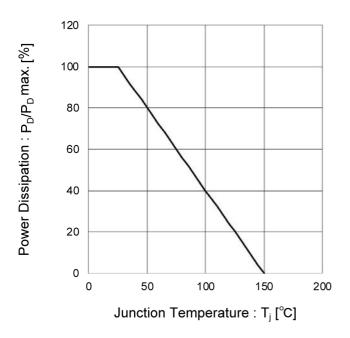
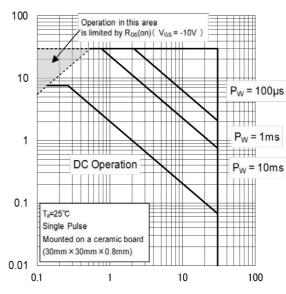


Fig.2 Maximum Safe Operating Area



Drain Current: -l<sub>D</sub> [A]

Drain - Source Voltage : -V<sub>DS</sub> [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

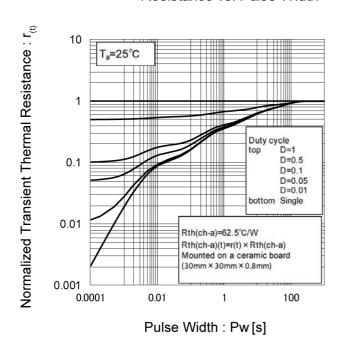
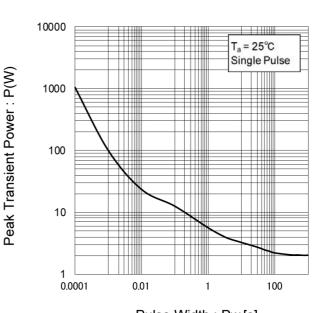


Fig.4 Single Pulse Maximum Power dissipation



Pulse Width: Pw[s]

Fig.5 Typical Output Characteristics(I)

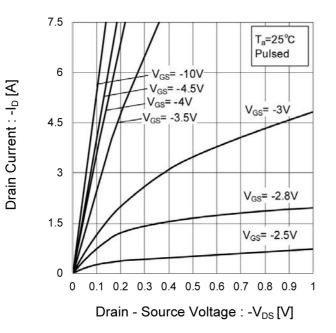
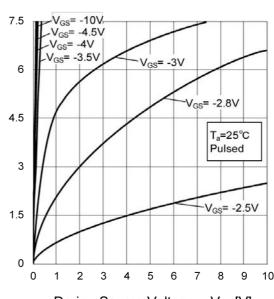


Fig.6 Typical Output Characteristics(II)



Drain Current : -I<sub>D</sub> [A]

Drain - Source Voltage : -V<sub>DS</sub> [V]

Fig.7 Breakdown Voltage vs. Junction Temperature

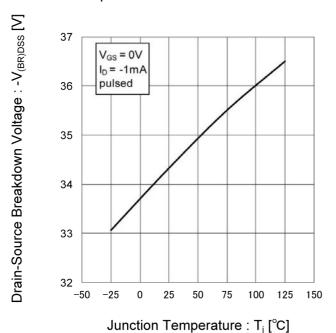


Fig.8 Typical Transfer Characteristics

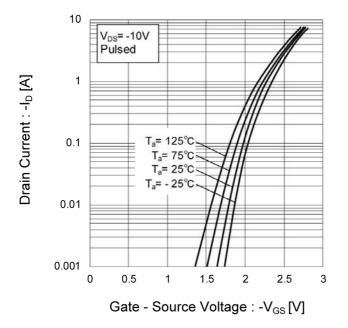
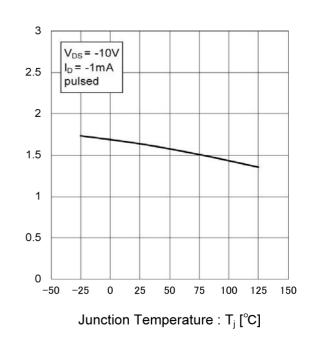


Fig.9 Gate Threshold Voltage vs. Junction Temperature



Gate Threshold Voltage :  $-V_{GS(th)}$  [V]

Fig.10 Transconductance vs. Drain Current

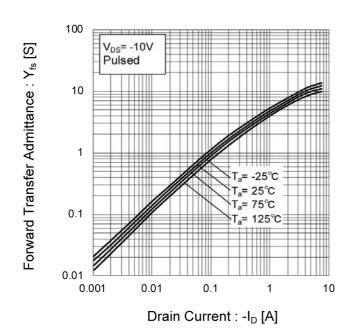


Fig.11 Drain Current Derating Curve

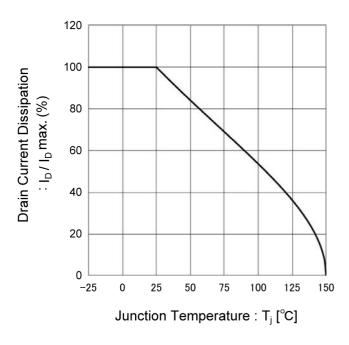


Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

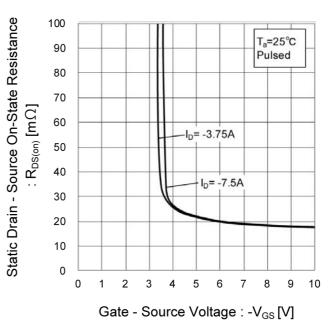


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

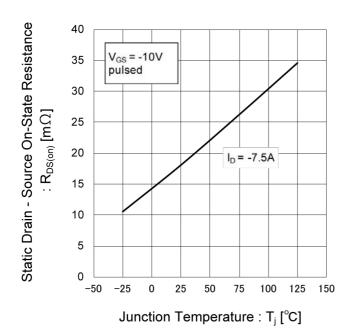


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current(I)

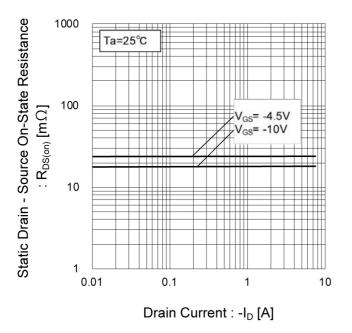


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

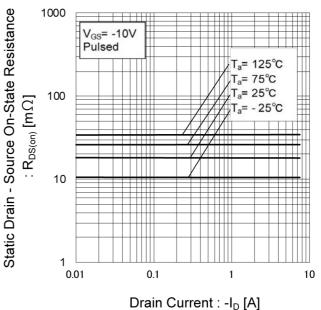
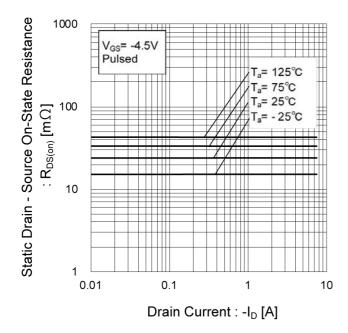


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current(III)



ROHM

Fig.17 Typical Capacitance vs. Drain - Source Voltage

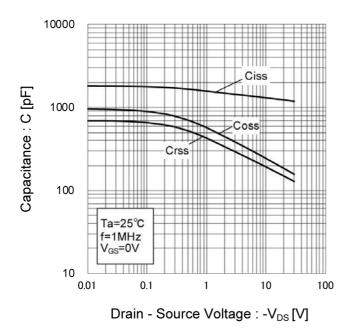


Fig.18 Switching Characteristics

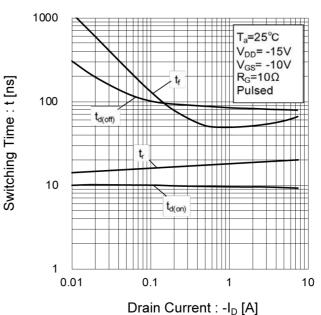


Fig.19 Dynamic Input Characteristics

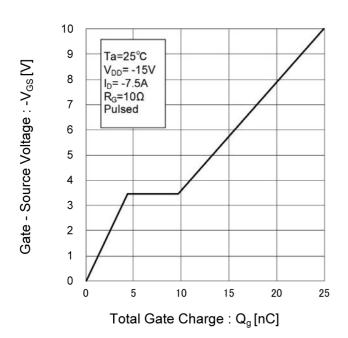
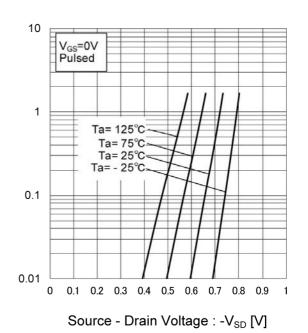


Fig.20 Source Current vs. Source Drain Voltage



Source Current : -I<sub>s</sub> [A]

# Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

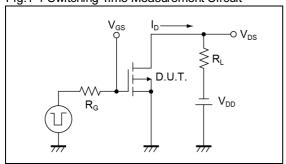


Fig.2-1 Gate Charge Measurement Circuit

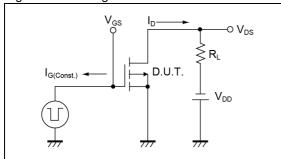


Fig.3-1 AVALANCHE MEASUREMENT CIRCUIT

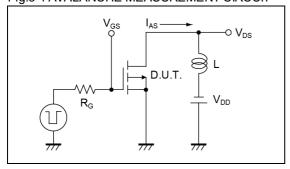


Fig.1-2 Switching Waveforms

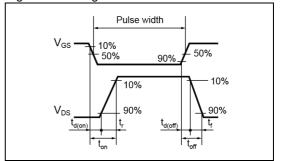


Fig.2-2 Gate Charge Waveform

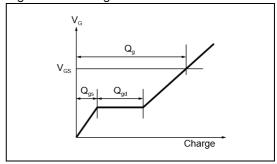
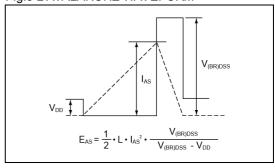
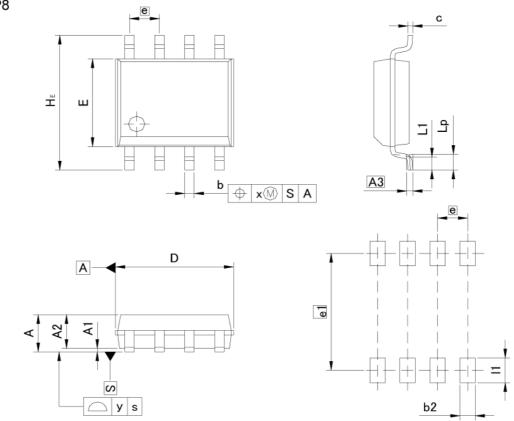


Fig.3-2 AVALANCHE WAVEFORM



# Dimensions

SOP8



Pattern of terminal position areas [Not a pattern of soldering pads]

| DIM - | MILIM | ETERS | INC   | HES   |
|-------|-------|-------|-------|-------|
| DIM   | MIN   | MAX   | MIN   | MAX   |
| Α     | €3    | 1.75  | -     | 0.069 |
| A1    | 0.    | 15    | 0.0   | 06    |
| A2    | 1.40  | 1.60  | 0.055 | 0.063 |
| A3    | 0.    | 25    | 0.0   | 10    |
| b     | 0.30  | 0.50  | 0.012 | 0.020 |
| С     | 0.10  | 0.30  | 0.004 | 0.012 |
| D     | 4.80  | 5.20  | 0.189 | 0.205 |
| E     | 3.75  | 4.05  | 0.148 | 0.159 |
| е     | 1.    | 27    | 0.0   | 50    |
| HE    | 5.70  | 6.30  | 0.224 | 0.248 |
| L1    | 0.50  | 0.70  | 0.020 | 0.028 |
| Lp    | 0.65  | 0.85  | 0.026 | 0.033 |
| x     | 0.15  |       | 0.0   | 06    |
| у     | 0.    | 10    | 0.0   | 04    |

| DIM | MILIMETERS      |      | INC             | HES   |
|-----|-----------------|------|-----------------|-------|
| DIM | MIN             | MAX  | MIN             | MAX   |
| b2  | <del>5</del> 8  | 0.65 | <del>57</del> 0 | 0.026 |
| e1  | 5.              | 5.15 |                 | 203   |
| 11  | <del>z</del> s. | 1.15 | <del>77</del> % | 0.045 |

Dimension in mm/inches



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| JAPAN   | USA      | EU         | CHINA    |
|---------|----------|------------|----------|
| CLASSⅢ  | CLASSⅢ   | CLASS II b | CLASSIII |
| CLASSIV | CLASSIII | CLASSⅢ     | CLASSIII |

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  - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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  - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
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  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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**Rev.001** 

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